

Amendments to the Specification

Please replace the title with the following amended title:

~~SEMICONDUCTOR DEVICE~~[[.]] METHOD OF MANUFACTURING A SEMICONDUCTOR PACKAGE FOR USE THEREIN, AND MANUFACTURING METHOD THEREOF HAVING SEMICONDUCTOR DEVICE MOUNTED THEREON AND ELONGATE OPENING THROUGH WHICH ELECTRODES AND PATTERNS ARE CONNECTED

Kindly amend the specification as follows:

Please replace the paragraph previously inserted at Page 1, between lines 3 and 4, with the following amended paragraph:

This is a divisional application of application Serial No. 09/062,720, filed April 20, 1998, now U.S. Patent No. 6,175,159, which is hereby incorporated by reference in its entirety for all purposes, and is related to subsequently filed copending divisional applications Serial No. 09/981,891 filed on October 19, 2001, now U.S. Patent No. 6,661,099, and Serial No. 10/690,627 filed on October 23, 2003.

Please replace the abstract with the following amended abstract:

A method of manufacturing a semiconductor package ~~is includes~~ including a substrate for mounting and fixing a semiconductor chip thereon and a connecting pattern, includes providing the[[.]] [[The]] substrate ~~is provided with an~~ [[a]] elongate

opening formed therein[.] ~~[[The]]~~, fixing the semiconductor chip ~~is fixed~~ with its surface
[[being]] mounted on the substrate and with its electrode being aligned within the
elongate opening[.] ~~[[The]]~~, and electrically connecting an electrode of the
semiconductor chip ~~is electrically connected~~ to the connecting pattern via wires through
the elongate opening. The elongate opening and the wires then are sealed with resin.